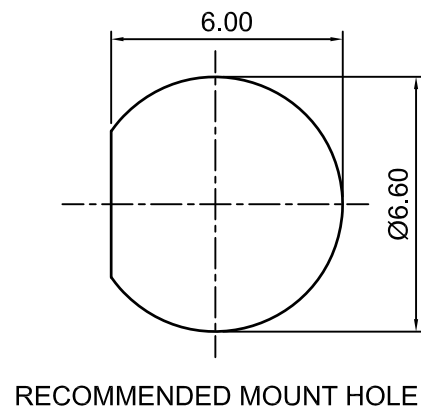
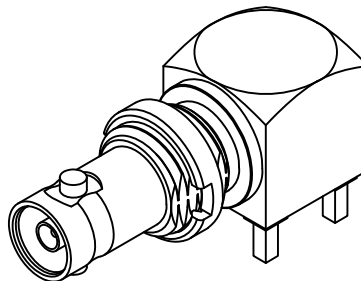
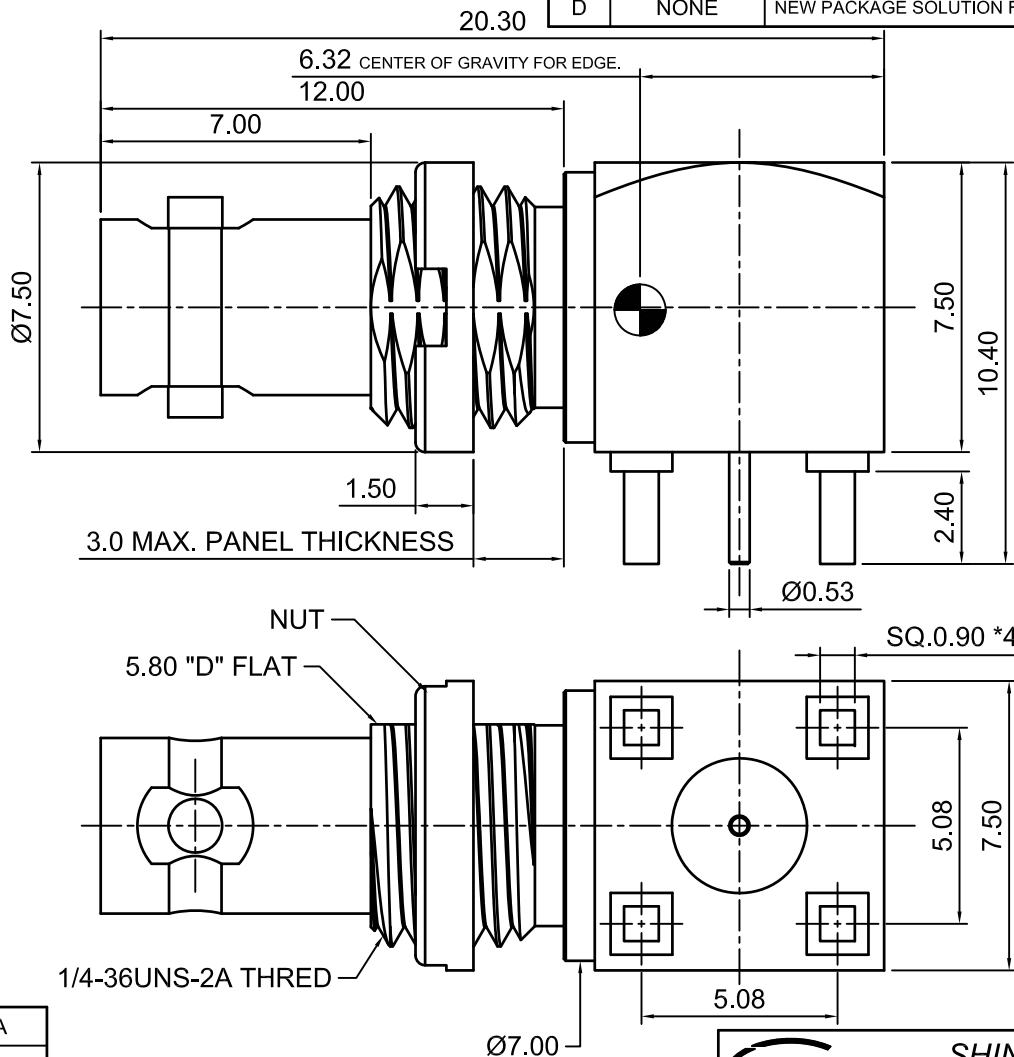
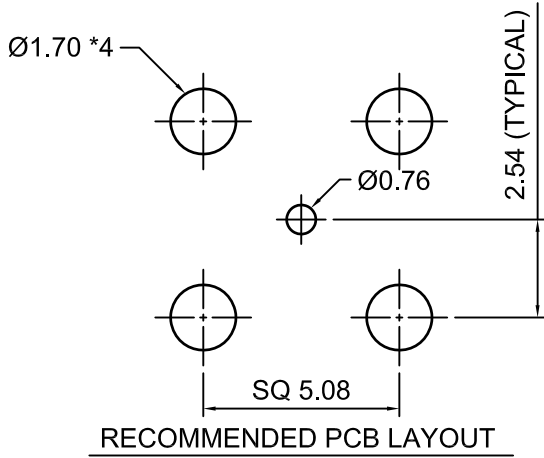


Customer code:	NONE	Part number:	OBFR100PCB-A701	Rev:	D	Changing log
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NOTE:

1. ELECTRICAL CHARACTERISTICS:
 - 1.1 FREQUENCY RANGE:DC~12GHz
 - 1.2 IMPEDANCE:75Ω
 - 1.3 VSWR:1.3 MAX @ 6GHz.
 - 1.4 INSULATION RESISTANCE: 5000MΩ MIN.
 - 1.5 CONTACT RESISTANCE
 - 1.5.1 CENTER CONTACT: 3 MΩ
 - 1.5.2 OUTER CONTACT: 2.5 MΩ
2. MECHANICAL CHARACTERISTICS:
 - 2.1 TEMPERATURE RANGE: -65°C~-165°C
 - 2.2 DURABILITY: 500 CYCLES.
3. ALL MATERIALS AND PROCESS ARE RoHS COMPLIANT.

Rev.	ECN#	Description	Changed by	Date
A	NONE	FIRST RELEASE.	M.YANG	2019-07-29
B	NONE	ADDITION SHEET-2, SOLDERING INFORMATION.	M.YANG	2019-11-08
C	NONE	CHANGING THE NUT AND REMOVING THE WASHER.	M.YANG	2019-11-26
D	NONE	NEW PACKAGE SOLUTION FOR SMT PROCESS.	M.YANG	2024-12-23



⑤	SPANNER NUT	BRASS	NICKEL	1EA
④	CONTACT PIN	BERYLLIUM COPPER	GOLD	1EA
③	INSULATOR	TEFLON	NATURAL	1EA
②	BODY-FRONT	BRASS	GOLD	1EA
①	BODY-BACK	BRASS	NICKEL	1EA
ITEM	NAME	MATERIAL	TREATMENT	QTY

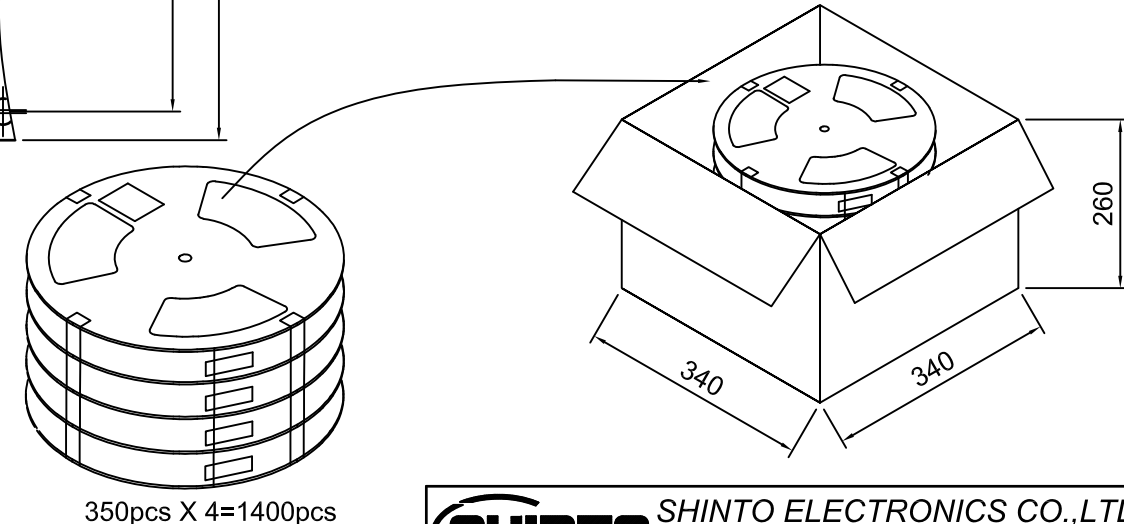
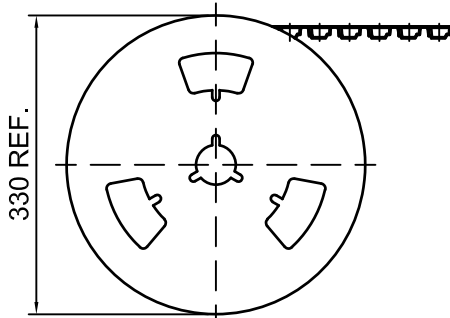
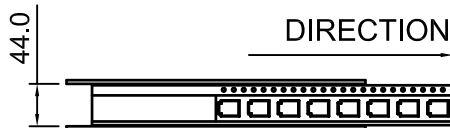
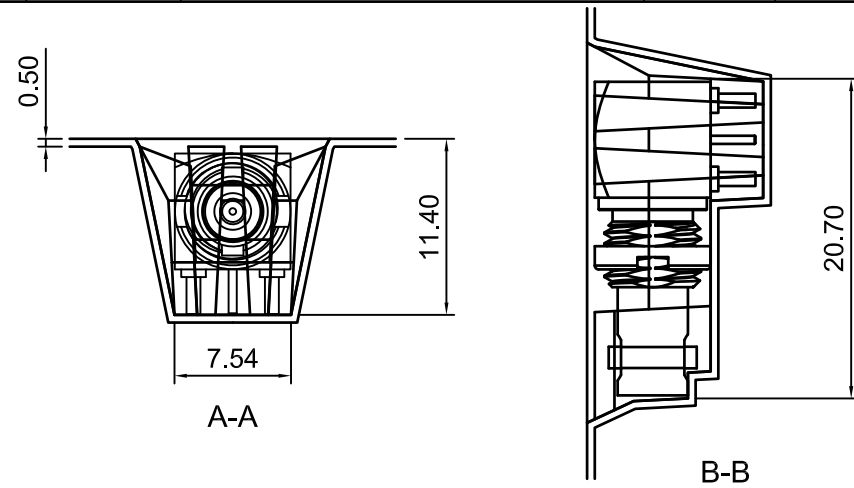
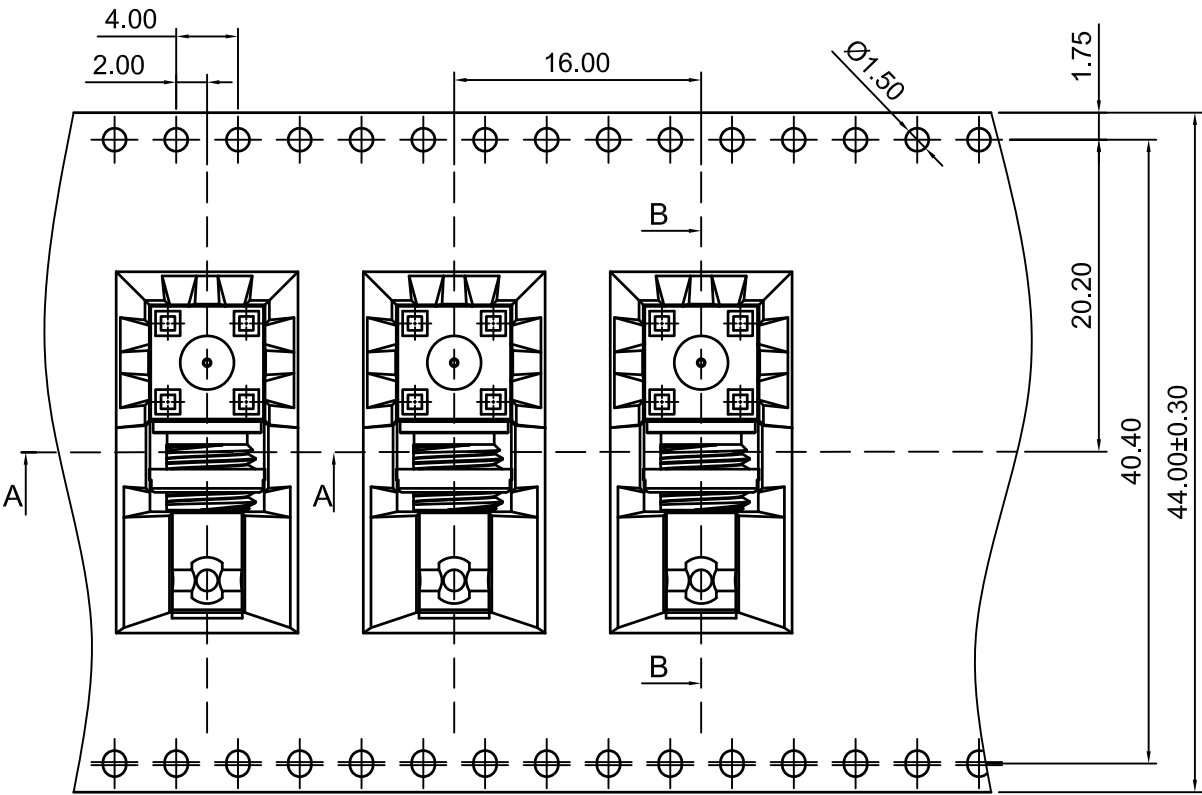
TOLERANCES UNLESS OTHERWISE SPECIFIED		
ONE PLACE DECIMAL	.X	±0.2
TWO PLACE DECIMAL	.XX	±0.1
THREE PLACE DECIMAL	.XXX	±0.05
HOLE DIA, VARIATION	.XX	N/A
ANGULAR DIMENSION		±3°

Signature		Shinto P/N: OBFR100PCB-A701			
Approved By:		Description: Micro-BNC jack R/A for PCB DIP mount			
Checked By:		Material:	See BOM	Treatment:	See BOM
Drawn By:	M.YANG	Unit: mm	Size: A4	Scale: 5:1	Sheet: 1 of 3

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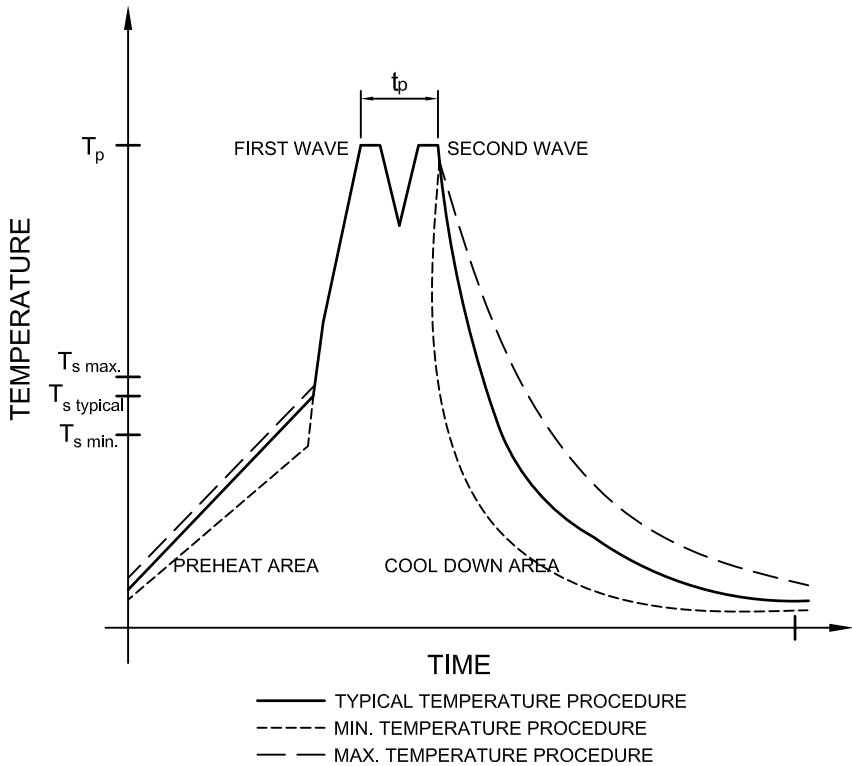


TOLERANCES UNLESS OTHERWISE SPECIFIED		
ONE PLACE DECIMAL .X		±0.20
TWO PLACE DECIMAL .XX		±0.1
THREE PLACE DECIMAL .XXX		±0.05
HOLE DIA. VARIATION .XX	N/A	
ANGULAR DIMENSION		±3°

Signature	
Approved By:	
Checked By:	
Drawn By:	M.YANG

SHINTO SHINTO ELECTRONICS CO.,LTD http://www.shinto-electronics.com	
Shinto P/N: OBFR100PCB-A701	
Description: Micro-BNC jack R/A for PCB DIP mount	
Material: See BOM	Treatment: See BOM
Unit: mm	Size: A4
Scale: 2:1	Sheet: 2 of 3

CLASSIFICATION WAVE SOLDERING PROFILE:



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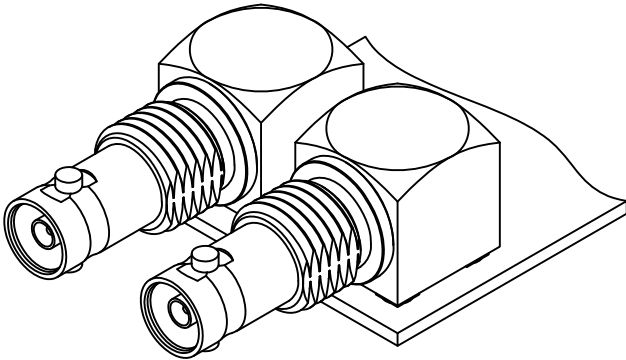
CLASSIFICATION WAVE SOLDERING PROFILE:

PROFILE FEATURE		PB-FREE ASSEMBLY	SN-PB ASSEMBLY
PREHEAT TEMPERATURE MIN.(1)	$T_{s\ min.}$	100°C	100°C
PREHEAT TEMPERATURE TYPICAL	$T_{s\ typical}$	120°C	120°C
PREHEAT TEMPERATURE MAX.	$T_{s\ max.}$	130°C	130°C
PREHEAT TIME t_s FROM $T_{s\ min}$ TO $T_{s\ max}$	t_s	70 SECONDS	70 SECONDS
RAMP-UP RATE	ΔT	150°C MAX.	150°C MAX.
PEAK TEMPERATURE	T_p	250°C ~ 260°C	230°C ~ 260°C
TIME OF ACTUAL PEAK TEMPERATURE	t_p	MAX. 10 SECONDS MAX. 5 SECONDS EACH WAVE	MAX. 10 SECONDS MAX. 5 SECONDS EACH WAVE
RAMP-DOWN RATE, MIN.		~ 2 K / SECONDS	~ 2 K / SECONDS
RAMP-DOWN RATE, TYPICAL		~ 3.5 K / SECONDS	~ 3.5 K / SECONDS
RAMP-DOWN RATE, MAX.		~ 5 K / SECONDS	~ 5 K / SECONDS
TIME 25°C TO 25°C		4 MINUTES	4 MINUTES

(1) REFER TO EN61760-1:2006

Soldering
The solder profile must comply with SHINTO technical soldering specification, otherwise this will void the warranty.
Other soldering methods are not verified and have to validated by the customer at his own risk.

Cleaning and washing
Parts are not constructed for washing, so washing can cause malfunction afterwards.
Cleaning agent that are used to clean the customer applications might damage or change the characteristics of the component, body pins and termination.



SHINTO ELECTRONICS CO.,LTD
http://www.shinto-electronics.com

TOLERANCES UNLESS OTHERWISE SPECIFIED			Signature		Shinto P/N: OBFR100PCB-A701			
			Approved By:		Description: Micro-BNC jack R/A for PCB DIP mount			
ONE PLACE DECIMAL	.X	±0.20	Checked By:		Material:	See BOM	Treatment:	See BOM
TWO PLACE DECIMAL	.XX	±0.1						
THREE PLACE DECIMAL	.XXX	±0.05	Drawn By:	M.YANG	Unit: mm	Size: A4	Scale: 5:1	Sheet: 2 of 3
HOLE DIA. VARIATION	.XX	N/A						
ANGULAR DIMENSION		±3°						

